

●WLP-5-03 Power Dissipation

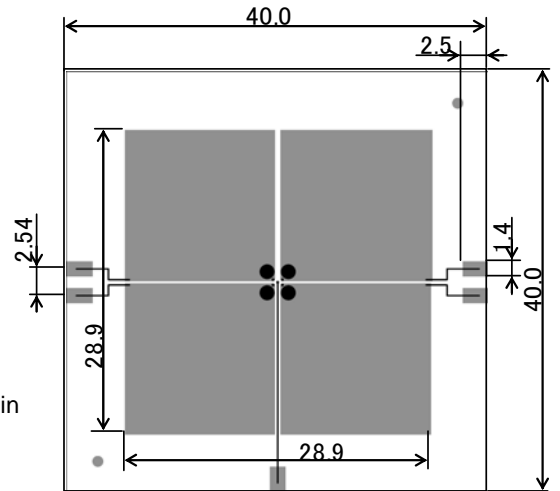
Power dissipation data for the WLP-5-03 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Conditions

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board Dimensions : 40mm×40mm (1600mm² in one side)
- Metal Area : 1st Metal Layer about 50%
2nd Inner Metal Layer about 50%
3rd Inner Metal Layer about 50%
4th Metal Layer about 50%
4 separations is each layer connected to each pin
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6mm
- Through-hole : 4 x 0.8 Diameter



2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	750	133.33
85	300	

